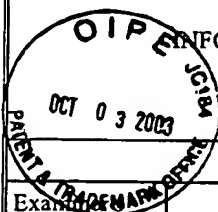


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INFORMATION DISCLOSURE CITATION
IN AN APPLICATION
(use several sheets if necessary)

Docket No.
P03,0217Serial No.
10/606,069Applicant
Gabric et alFiling Date
June 25, 2003Group Art Unit
2812-2818

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Examiner Initials	Document Number	Date	Name	Class	Subclass	Filing Date If appropriate
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	AI					

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<i>DL</i>	AP	United States Patent Application Publication no. US 2001/0002732 of Schwarzl et al, published June 7, 2001
	AQ	M.T. Bohr, "Interconnect Scaling - The Real Limiter to High Performance ULSI", <u>IEDM 95</u> , pages 241 - 244
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Examiner

[Signature]

Date Considered

7/10/04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.